

ABSTRACT OF DISCLOSURE

In an electronic component mounting method in which electronic components are sucked/held by plural respective nozzles provided on a mounting head so as to be mounted on electronic component mounting portions of a board, such a mounting operation is sequentially carried out as to all of the electronic components, in which the electronic components are sucked/held by the plural nozzles; an electronic component sucked/held by one of the plural nozzles is provisionally positioned above one electronic component mounting portion; both this electronic component and the electronic component mounting portion are observed by an observation head which is located between the board and the mounting head; a relative position detecting operation for detecting a relative positional relationship between this electronic component and the electronic component mounting portion is carried out as to all of the electronic components held by the mounting head; and the electronic component is positioned with respect to the electronic component mounting portion so as to be mounted thereon while the detected relative positional relationship is reflected.

[Selected drawing] Fig. 11